


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	POWER AND DISCRETE PRODUCTS/24/14795	
1.3 Title of PCN	Transfer of assembly and test line qualification with molding compound replacement for SiC 1200V devices (TO220AC package)	
1.4 Product Category	STPSC10H12D STPSC15H12D STPSC20H12D STPSC2H12D STPSC5H12D	
1.5 Issue date	2024-06-18	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Stephane CHAMARD
2.1.2 Marketing Manager	Philippe LEGER
2.1.3 Quality Manager	Jean-Paul REBRASSE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Product transfer from one site to another site, even if test or process line is qualified	Subcontractor (China)

4. Description of change

	Old	New
4.1 Description	Assembly and Test & Finishing in ST Shenzhen (China) Resin supply by Kyocera Singapore	Assembly and Test & Finishing in a subcontractor (China) New resin
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No	

5. Reason / motivation for change

5.1 Motivation	ST Shenzhen has decided to phase out TO220AC line to extend production capacity for other packages. Molding compound discontinuation from current resin supplier.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability of the change will be ensured by Finished Good/Type print on carton labels (New FG ending by F).
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7. Timing / schedule

7.1 Date of qualification results	2024-06-07
7.2 Intended start of delivery	2024-09-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14795 24021QRP.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-06-18

9. Attachments (additional documentations)

14795 Public product.pdf
14795 PCN TO220AC SiC transfer and molding.pdf
14795 24021QRP.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STPSC10H12D	

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